



JORX223 Series

DIP7, DC Input, TRIAC Output, Solid State Relay

Description

The JORX223 series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo triac to drive a power triac in a plastic DIP8 package with different lead forming options.

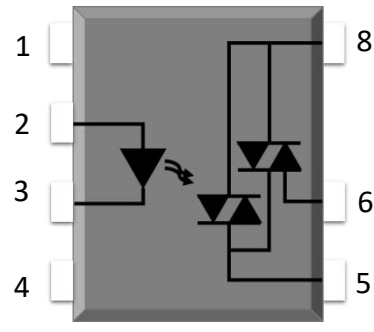
Features

- High isolation 5000 VRMS
- DC input with triac output
- Operating temperature range - 40 °C to 85 °C
- RoHS & REACH Compliance
- MSL class 1
- Regulatory Approvals
 - UL
 - VDE

Applications

- Solenoid/valve controls
- Lighting controls
- Motor controls
- Temperature controls
- Static AC power switches
- Solid state relays
- Interfacing microprocessors to 115 to 240VAC peripherals

SCHEMATIC

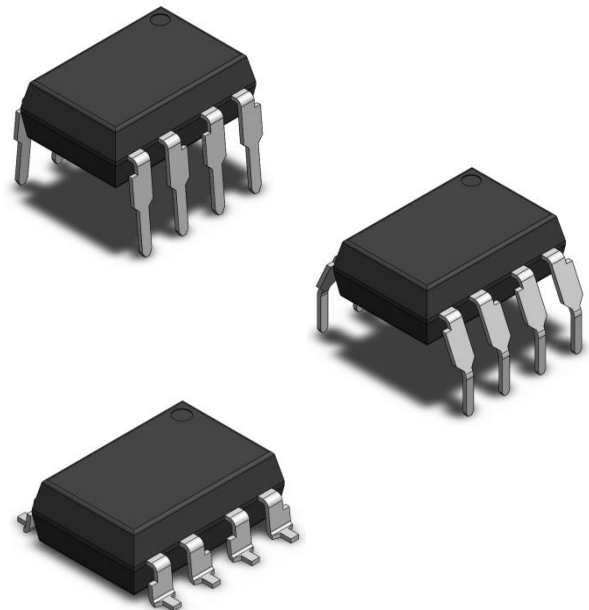


JORX223 Series (RP Type)

PIN DEFINITION

- | | |
|------------|-------------|
| 1. NC | 8. Terminal |
| 2. Anode | |
| 3. Cathode | 6. Terminal |
| 4. NC | 5. Gate |

PACKAGE OUTLINE



ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	VALUE	UNIT	NOTE
INPUT				
Forward Current	I_F	60	mA	
Peak Forward Current	I_{FP}	1	A	1
Reverse Voltage	V_R	6	V	
Junction Temperature	T_j	125	°C	
Input Power Dissipation	P_i	100	mW	
OUTPUT				
Off-state Output Terminal Voltage	V_{DRM}	600	V	
On-state RMS Current	JOR0223	0.3	A	
	JOR1223	0.6		
	JOR2223	0.9		
	JOR3223	1.2		
Non-repetitive Surge Current PW=100μs, 120pps	JOR0223	3	A	
	JOR1223	6		
	JOR2223	9		
	JOR3223	12		
Junction Temperature	T_j	125	°C	
COMMON				
Total Power Dissipation	P_{tot}	400	mW	
Isolation Voltage	V_{iso}	5000	V _{rms}	1
Operating Temperature	T_{opr}	-40~85	°C	
Storage Temperature	T_{stg}	-40~125	°C	
Soldering Temperature	T_{sol}	260	°C	2

Note 1. 100μs pulse, 100Hz frequency

Note 2. AC For 1 Minute, R.H. = 40 ~ 60%

Note 3. For 10 seconds

ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C							
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITION	NOTE
INPUT							
Forward Voltage	V _F	-	1.24	1.4	V	I _F =10mA	
Reverse Current	I _R	-	-	10	μA	V _R =6V	
Input Capacitance	C _{in}	-	30	-	pF	V=0, f=1kHz	
OUTPUT							
Peak Off-state Current, Either Direction	I _{DRM}	-	-	100	μA	V _{DRM} =600V I _F =0	3
Peak On-state Current, Either Direction	V _{TM}	-	0.8	2.5	V	I _{TM} = I _{TM} Rated	
Critical Rate of Rise of Off-state Voltage Breakdown Voltage	dV/dt	1000	-	-	V	V _{PEAK} =600V	
TRANSFER CHARACTERISTICS							
LED Trigger Current	I _{FT}	-	-	10	mA	Terminal Voltage = 6V RL=100 Ω	
Holding Current Saturation Voltage	I _H	-	-	25	mA	-	
Isolation Resistance	R _{iso}	10 ¹²	10 ¹⁴	-	Ω	DC500V, 40 ~ 60% R.H.	
Floating Capacitance	C _{io}	-	0.25	1	pF	V=0, f=1MHz	
ZERO CROSSING							

Note3. Test voltage must be applied within dV/dt rating.

CHARACTERISTIC CURVES

Fig.1 Forward Current vs. Forward Voltage

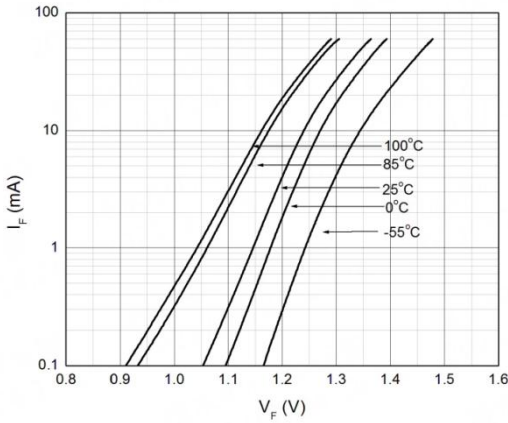


Fig.2 Off-state Terminal Current vs. Ambient Temperature

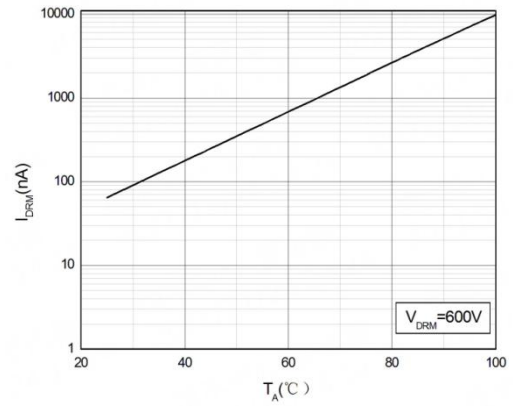


Fig.3 Normalized Off-state Terminal Voltage vs. Ambient Temperature

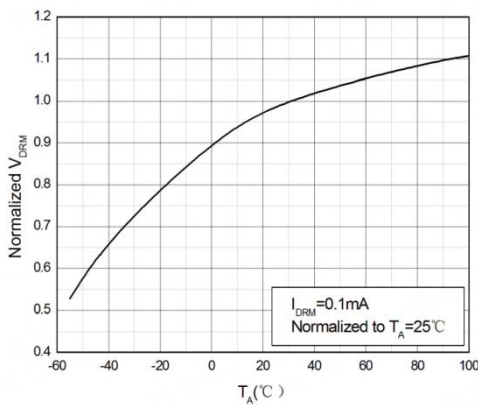


Fig.4 Normalized Trigger Current vs. LED Trigger Pulse Width

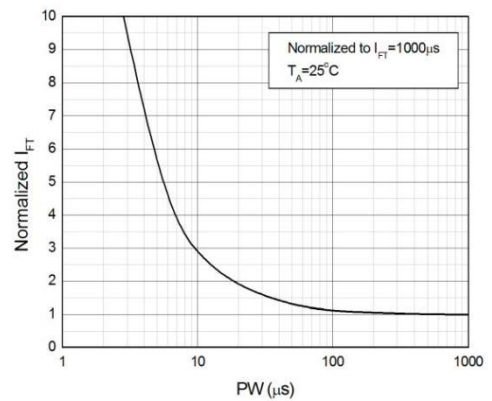


Fig.5 Normalized Trigger Current vs. Ambient Temperature

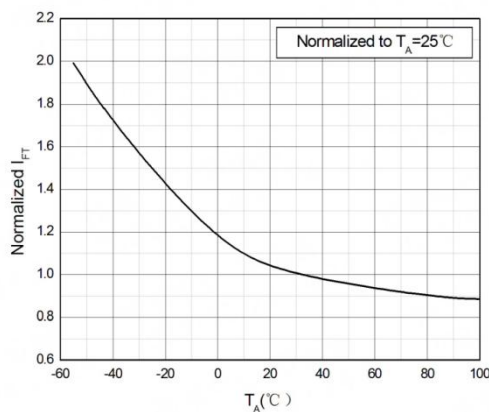
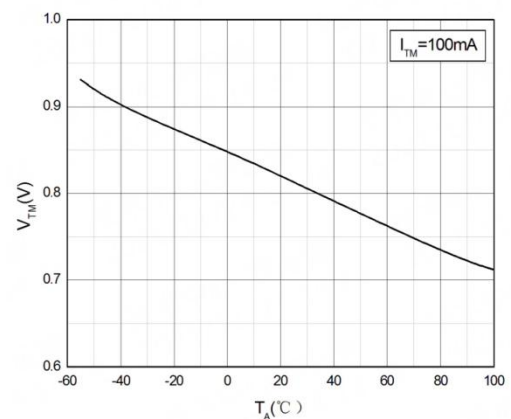


Fig.6 On-state Terminal Voltage vs. Ambient Temperature



CHARACTERISTIC CURVES

Fig.7 On-state Terminal Voltage vs. On-state Terminal Current

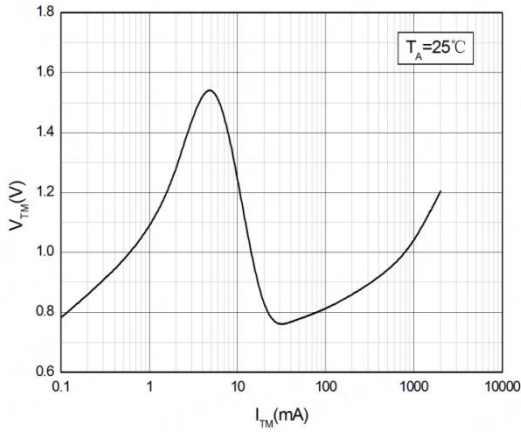


Fig.8 Holding Current vs. Ambient Temperature

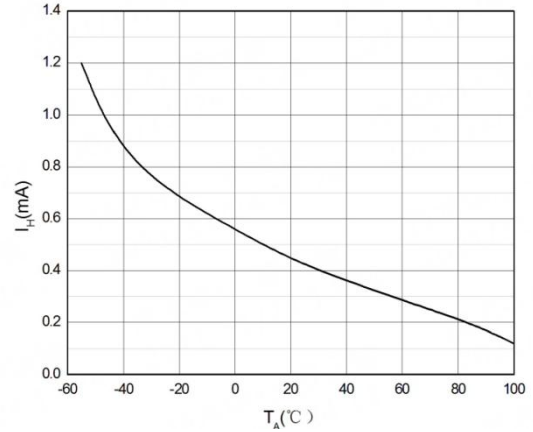


Fig.9 Turn On Time vs. Forward Current

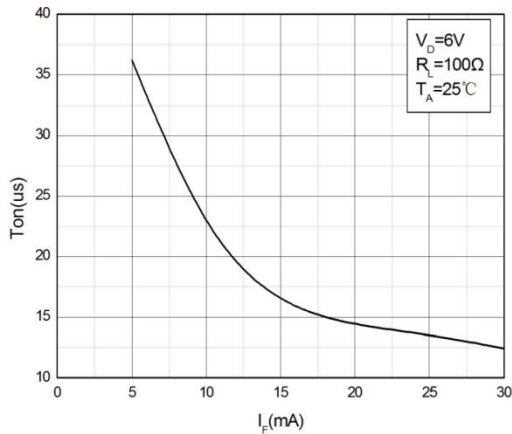
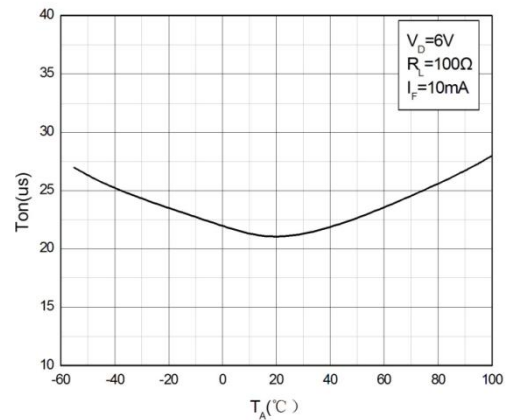


Fig.10 Turn On Time vs. Ambient Temperature



TEST CIRCUITS

Fig.11 Test Circuits of Turn On Time

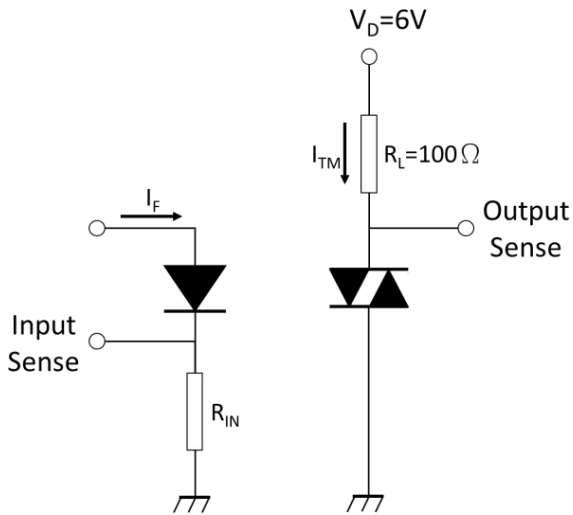


Fig.12 Waveforms of Turn On Time

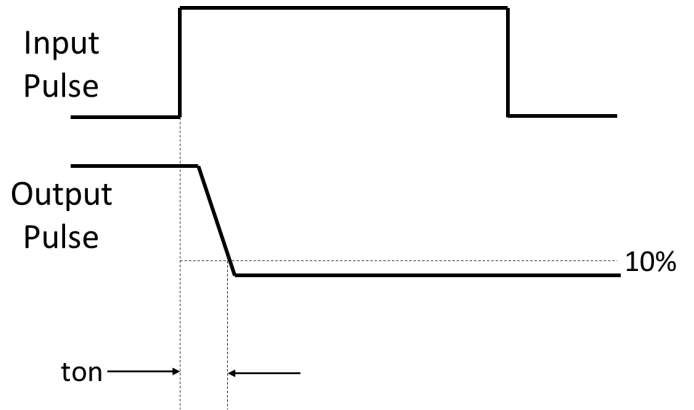


Fig.13 Test Circuits of dV/dt

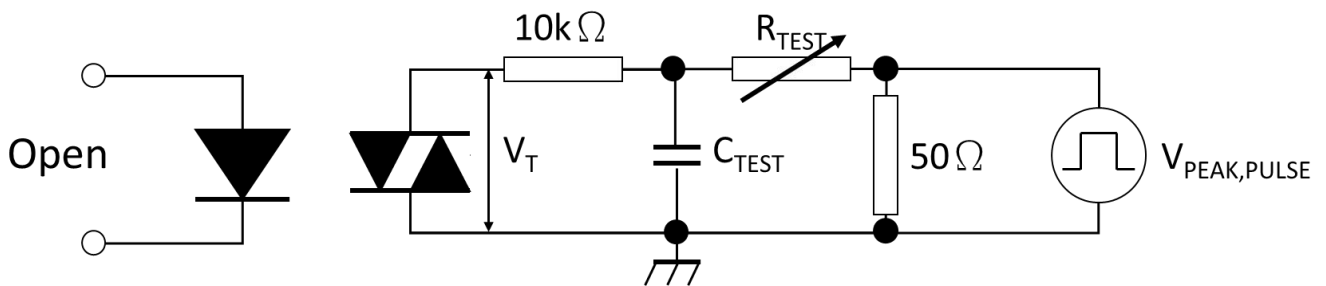
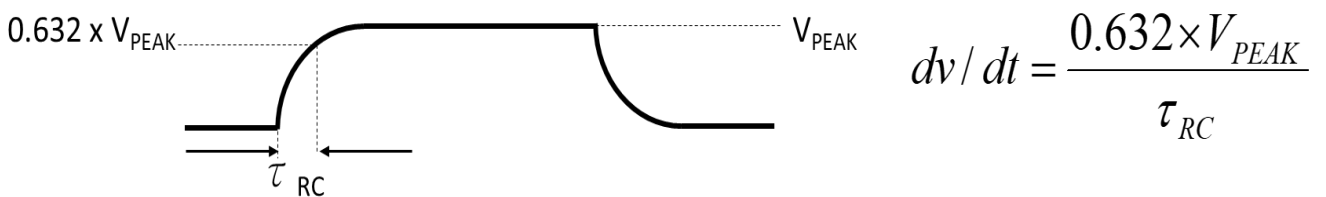
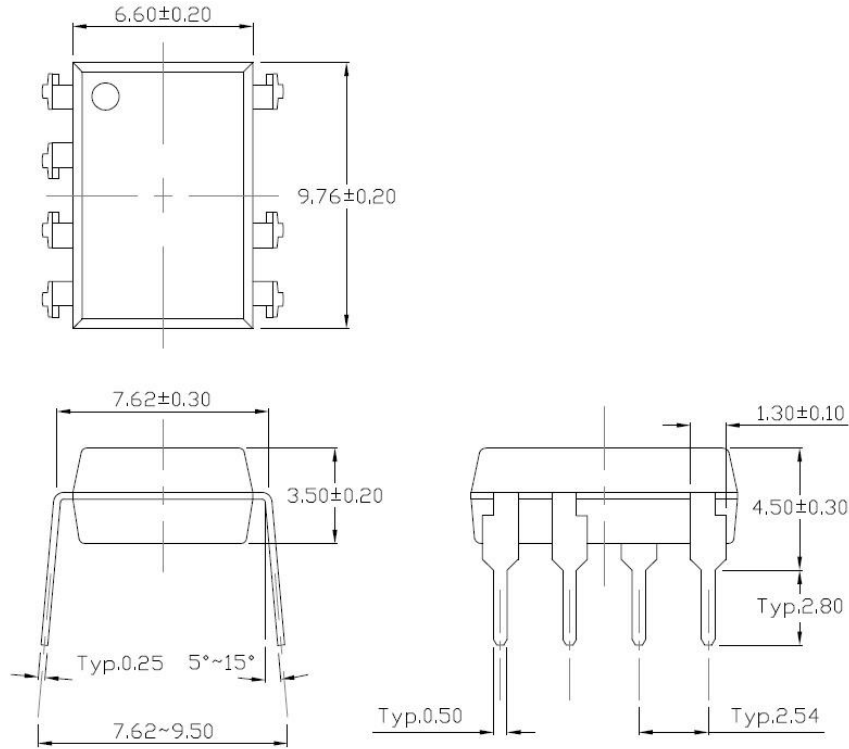


Fig.14 Waveforms of dV/dt

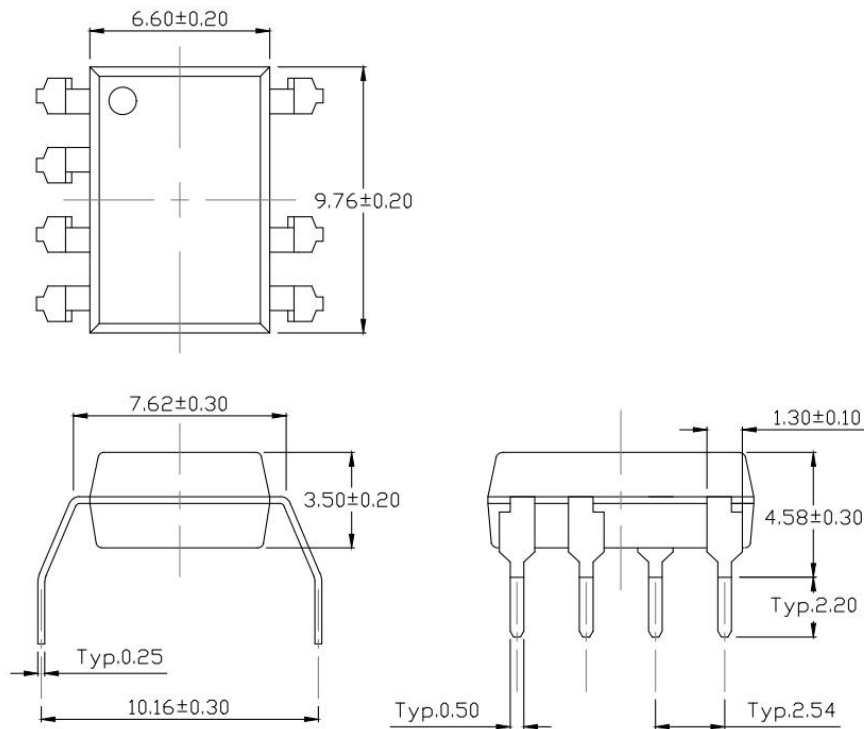


PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

Standard DIP – Through Hole (DIP Type)

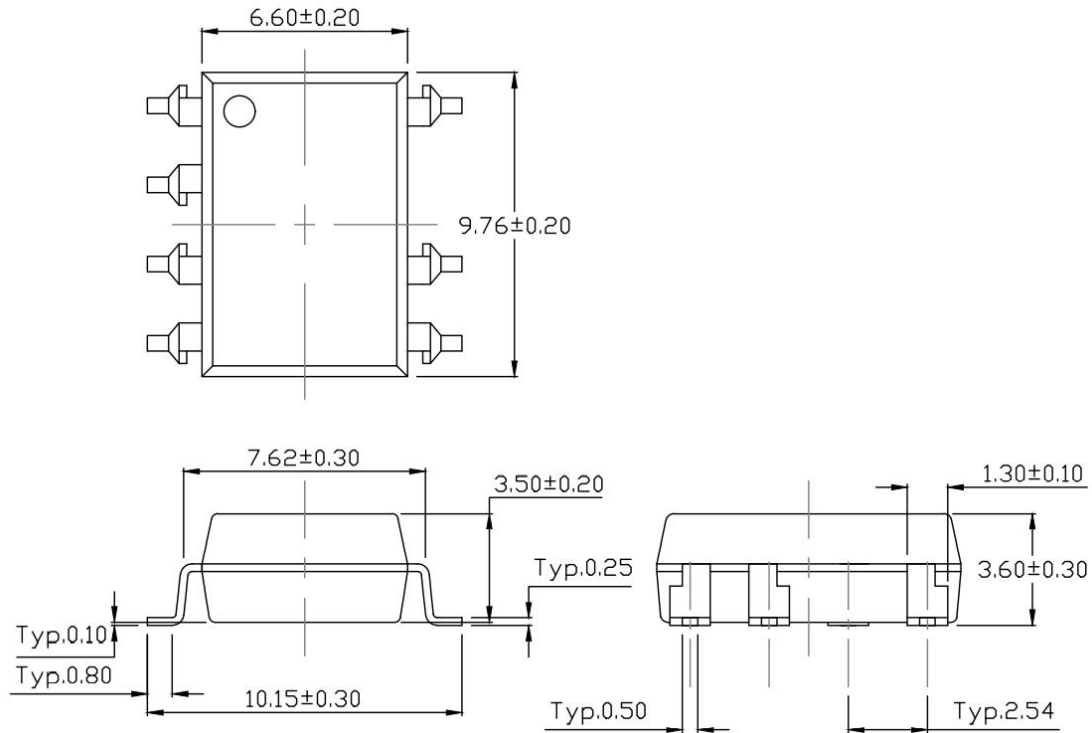


Gullwing (400mil) Lead Forming – Through Hole (M Type)



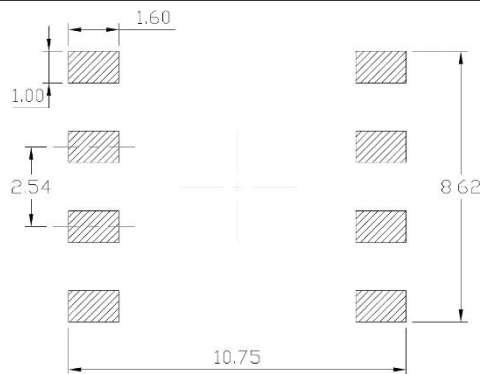
PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

Surface Mount (Low Profile) Lead Forming (SL Type)



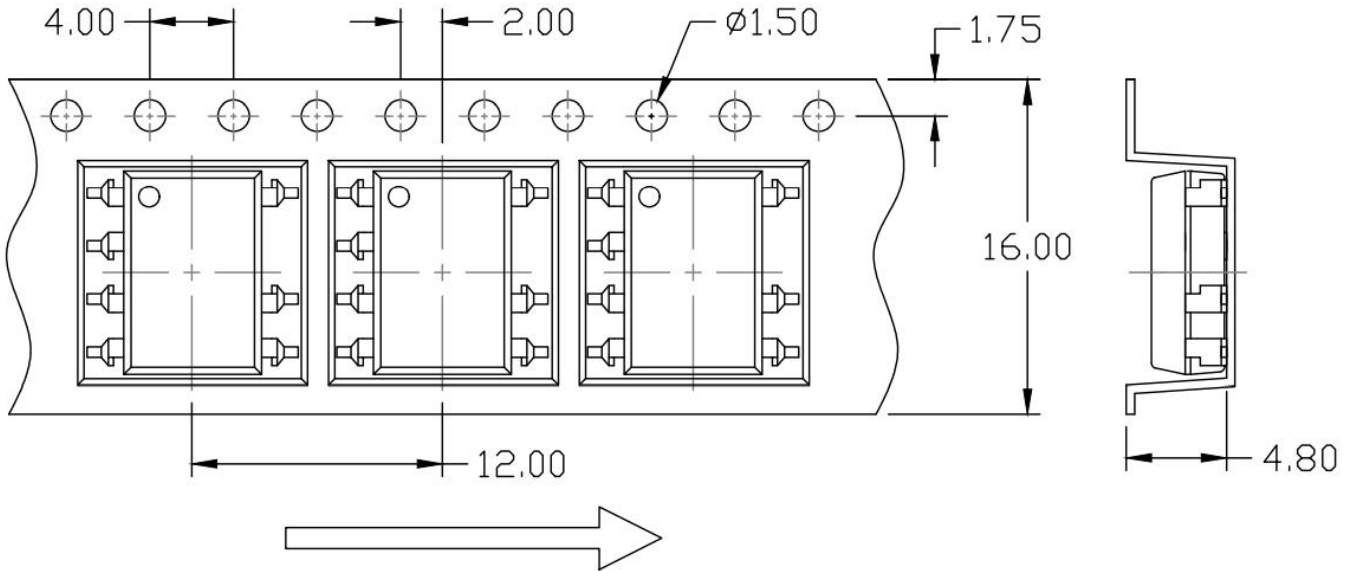
Recommended Solder Mask (Dimensions in mm unless otherwise stated)

Surface Mount Lead Forming & Surface Mount (Low Profile) Lead Forming

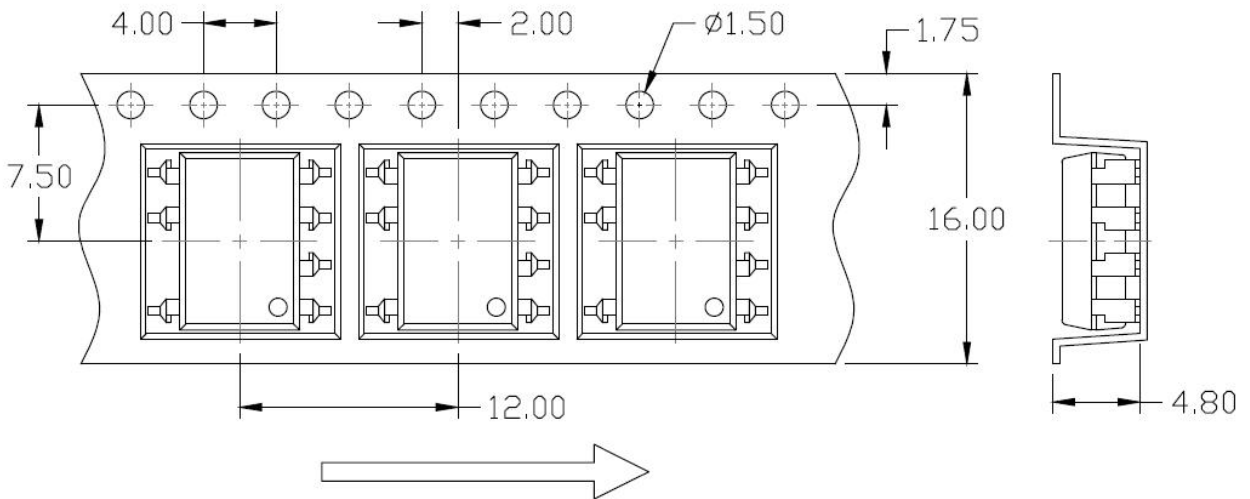


Carrier Tape Specifications (Dimensions in mm unless otherwise stated)

Option S(T1) & SL(T1)

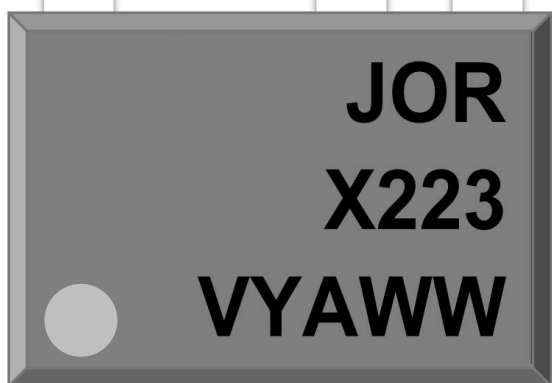


Option S(T2) & SL(T2)



ORDERING AND MARKING INFORMATION

MARKING INFORMATION



JOR : Company Abbr.
 X223 : Part Number & Rank
 V : VDE Option
 Y : Fiscal Year
 A : Manufacturing Code
 WW : Work Week

ORDERING INFORMATION

JORX223(Y)(Z)-GV

JOR – Company Abbr.
 X223 – Part Number & Rank (X=0/1/2/3)
 Y – Lead Form Option (M/SL/None)
 Z – Tape and Reel Option (T1/T2)
 G – Material Option
 (G: Green, None: Non-Green)
 V – VDE Option (V or None)

LABEL INFORMATION

 捷捷微电（深圳）有限公司
 JIEJIE MICROELECTRONICS (Shenzhen) Co Ltd

Part No.:XXXXXXXXX Bin Code: X



Lot No.: XXXXXXXXXXX

Date Code: XXXX

QTY: XXX PCS

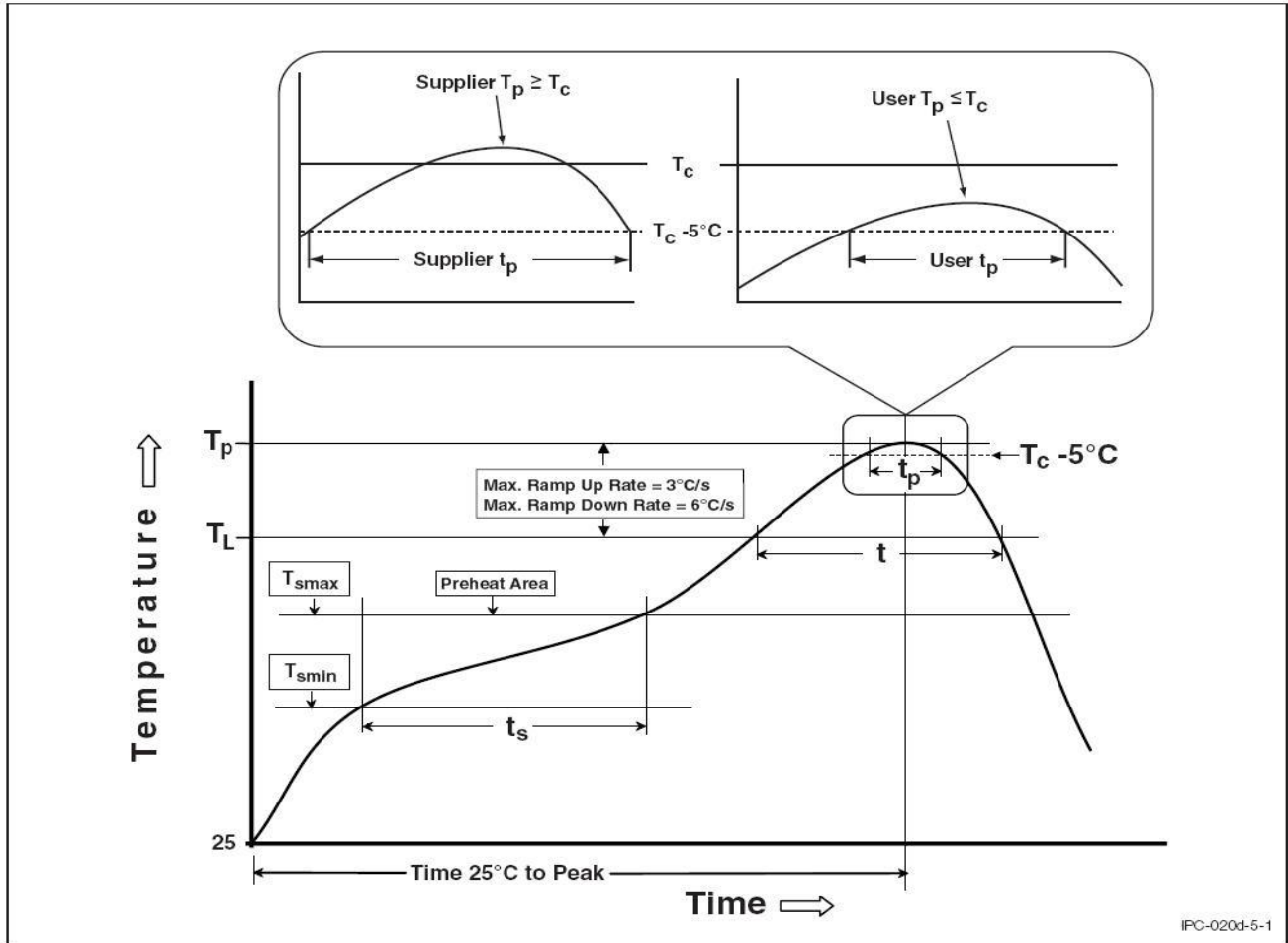


PACKING QUANTITY

Option	Quantity	Quantity – Inner box	Quantity – Outer box
None	40 Units/Tube	30 Tubes/Inner box	10 Inner box/Outer box = 12k Units
M	40 Units/Tube	30 Tubes/Inner box	10 Inner box/Outer box = 12k Units
SL(T1)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units
SL(T2)	1000 Units/Reel	3 Reels/Inner box	5 Inner box/Outer box = 15k Units

REFLOW INFORMATION

REFLOW PROFILE



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	100	150°C
Temperature Max. (T _{smax})	150	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.	3°C/second max.
Liquidous Temperature (T _L)	183°C	217°C
Time (t _L) Main Tained Above (T _L)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

DISCLAIMER

- JIEJIE is continually improving the quality, reliability, function and design. JIEJIE reserves the right to make changes without further notices.
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- This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or lifesaving applications or any other application which can result in human injury or death.
- Please contact JIEJIE sales agent for special application request.
- Immerge unit's body in solder paste is not recommended.
- Parameters provided in datasheets may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated in each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify JIEJIE's terms and conditions of purchase, including but not limited to the warranty expressed therein.
- Discoloration might be occurred on the package surface after soldering, reflow or long-time use. It neither impacts the performance nor reliability.